

MiniSKiiP<sup>®</sup>1

3-phase bridge rectifier + brake chopper + 3-phase bridge inverter

SKiiP 12NAB066V1

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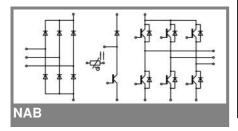
- Trench IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

#### Typical Applications\*

- Inverter up to 5 kVA
- Typical motor power 2,2 kW

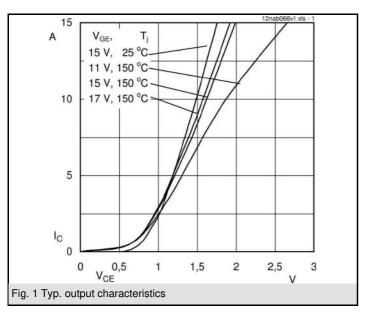
#### Remarks

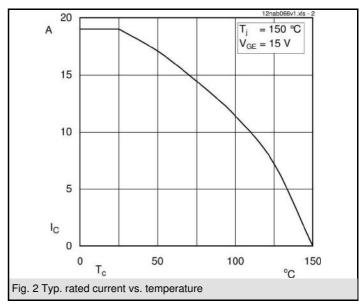
- Case temperature limited to T<sub>C</sub>= 125°C max.
- · Product reliability results are valid for T<sub>i</sub>=150°C
- SC data:  $t_p \le 6$  s;  $V_{GE} \le 15$  V;  $T_j$  = 150°C;  $V_{CC}$  = 360 V  $V_{CEsat}$ ,  $V_F$  = chip level values

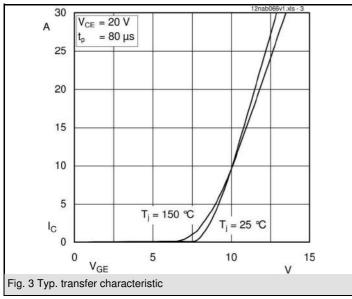


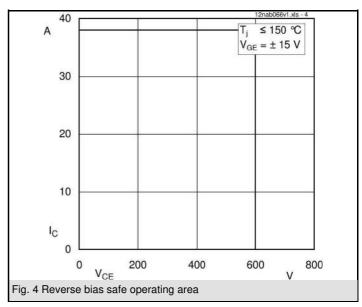
<b>Absolute Maximum Ratings</b> T <sub>S</sub> = 25°C, unless otherwise specified							
Symbol	Conditions	Values					
IGBT - Inverter, Chopper							
$V_{CES}$		600	V				
I <sub>C</sub>	$T_s = 25 (70) ^{\circ}\text{C}, T_i = 150 ^{\circ}\text{C}$	19 (14)	Α				
I <sub>C</sub>	$T_s = 25 (70) ^{\circ}\text{C},  T_j = 175 ^{\circ}\text{C}$	20 (16)	Α				
I <sub>CRM</sub>	t <sub>p</sub> = 1 ms	20	Α				
$V_{GES}$		± 20	V				
Diode - Inverter, Chopper							
I <sub>F</sub>	$T_s = 25 (70) ^{\circ}C, T_i = 150 ^{\circ}C$	20 (15)	Α				
I <sub>F</sub>	$T_s = 25 (70) ^{\circ}C, T_j = 175 ^{\circ}C$	20 (18)	Α				
I <sub>FRM</sub>	t <sub>p</sub> = 1 ms	20	Α				
Diode - Rectifier							
$V_{RRM}$		800	V				
I <sub>F</sub>	T <sub>s</sub> = 70 °C	35	Α				
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180 °, T <sub>j</sub> = 25 °C	220	Α				
i²t	$t_p = 10 \text{ ms, sin } 180 ^\circ, T_j = 25 ^\circ\text{C}$	240	A²s				
I <sub>tRMS</sub>	per power terminal (20 A / spring)	20	Α				
T <sub>j</sub>	IGBT, Diode	-40+175	°C				
T <sub>stg</sub>		-40+125	°C				
V <sub>isol</sub>	AC, 1 min.	2500	V				

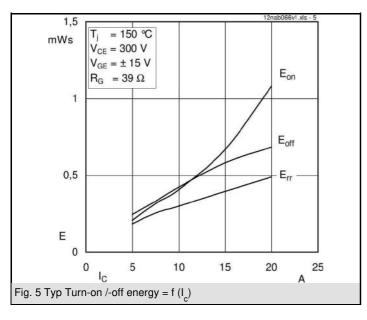
<b>Characteristics</b> T <sub>S</sub> = 25°C, unless otherwis					ecified			
Symbol	Conditions	min.	typ.	max.	Units			
IGBT - Inverter, Chopper								
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 10 A, T <sub>i</sub> = 25 (150) °C	1,1	1,45 (1,65)	1,85 (2,05)	V			
$V_{GE(th)}$	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 1 mA		5,8		V			
V <sub>CE(TO)</sub>	T <sub>i</sub> = 25 (150) °C		0,9 (0,7)	1,1 (1)	V			
$r_{CE}$	T <sub>i</sub> = 25 (150) °C		60 (100)	80 (110)	mΩ			
C <sub>ies</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,58		nF			
C <sub>oes</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,12		nF			
C <sub>res</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,04		nF			
R <sub>CC'+EE'</sub>	spring contact-chip T <sub>s</sub> = 25 (150 )°C				mΩ			
$R_{th(j-s)}$	per IGBT		2		K/W			
t <sub>d(on)</sub>	under following conditions		25		ns			
t <sub>r</sub>	$V_{CC} = 300 \text{ V}, V_{GE} = \pm 15 \text{V}$		25		ns			
$t_{d(off)}$	I <sub>Cnom</sub> = 10 A, T <sub>j</sub> = 150 °C		190		ns			
t <sub>f</sub>	$R_{Gon} = R_{Goff} = 39 \Omega$		40		ns			
$E_{on} \left( E_{off} \right)$	inductive load		0,41 (0,3)		mJ			
Diode - In	verter, Chopper							
$V_F = V_{EC}$	I <sub>F</sub> = 10 A, T <sub>i</sub> = 25 (150) °C		1,3 (1,3)	1,6 (1,6)	V			
$V_{(TO)}$	T <sub>i</sub> = 25 (150) °C		0,9 (0,8)	1 (0,9)	V			
r <sub>T</sub>	T <sub>i</sub> = 25 (150) °C		40 (50)	60 (70)	mΩ			
$R_{th(j-s)}$	per diode		2,5		K/W			
I <sub>RRM</sub>	under following conditions		15,8		Α			
Q <sub>rr</sub>	I <sub>Fnom</sub> = 10 A, V <sub>R</sub> = 300 V		1,5		С			
E <sub>rr</sub>	V <sub>GE</sub> = 0 V, T <sub>i</sub> = 150°C		0,42		mJ			
	di <sub>F</sub> /dt = 810 A/ s							
Diode -Re	ctifier							
$V_{F}$	I <sub>Fnom</sub> = 15 A, T <sub>i</sub> = 25 °C		1,1		V			
V <sub>(TO)</sub>	T <sub>i</sub> = 150 °C		0,8		V			
r <sub>T</sub>	T <sub>i</sub> = 150 °C		20		mΩ			
R <sub>th(j-s)</sub>	per diode		1,5		K/W			
	ure Sensor				1			
R <sub>ts</sub>	3 %, T <sub>r</sub> = 25 (100) °C		1000(1670)		Ω			
Mechanical Data								
W		ĺ	35		g			
M <sub>s</sub>	Mounting torque	2		2,5	Nm			

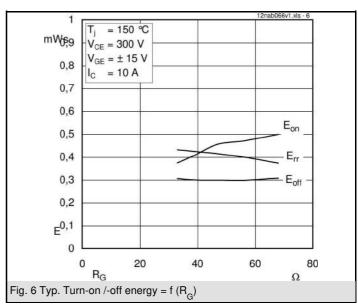


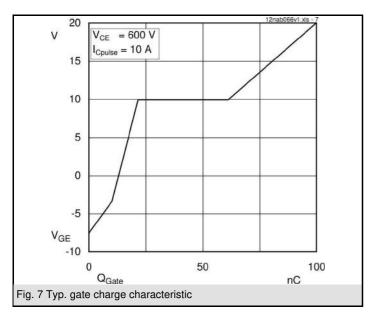


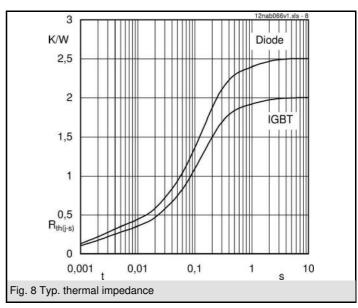


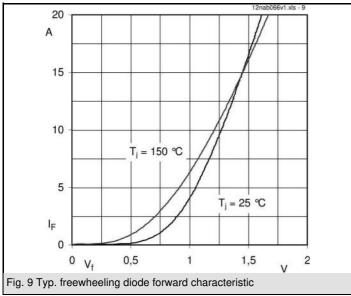


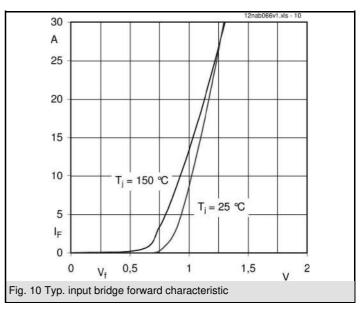


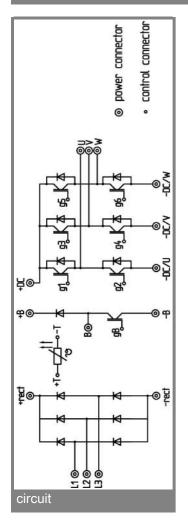


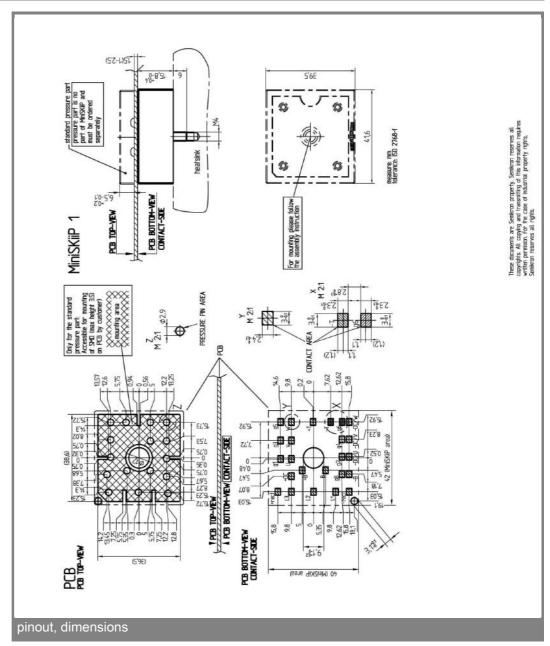












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

#### \*IMPORTANT INFORMATION AND WARNINGS

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